



## APPENDIX

## Changes to Claims:

The following is a marked-up version of the amended claims:

1. (Twice Amended) A semiconductor apparatus, comprising:

a substrate main body having a delineated mounting surface for mounting the semiconductor device;

a plurality of leads formed on the mounting surface, the plurality of leads radially extending from a peripheral area toward a central area of the substrate main body; and

a plurality of conduction sections each defining at least part of an external terminal and with substantially rectangular delineating fabrication alignment contour lines, the conduction sections being electrically connected to the leads.

7. (Twice Amended) A semiconductor apparatus, comprising:

a semiconductor device having a plurality of electrodes;

a substrate main body;

a plurality of leads formed on the substrate main body, the plurality of leads radially extending from a peripheral area toward a central area of the substrate main body; and

a plurality of conduction sections formed on the substrate main body and with substantially rectangular delineating fabrication alignment contour lines, the conduction sections being electrically connected to the leads, and one of the conduction sections defining an external terminal.